Contact Name  Title - Contact  Product-Env-Stewards  Product Enviro Compliance  Authorized Representative*  Product-Env-Stewards  Product Enviro Compliance  NA  Product-Env-Stewards@onsemi.com  Phone - Representative*  Phone - Representative*  Email - Representative*  Product-Env-Stewards@onsemi.com  Product-Env-Stewards  Product-Env-Stewards@onsemi.com  Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  Unitem Number	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lo level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company unique ID  Unique ID Authority  Response Date*  2023-06-08  Contact Name  Title - Contact  Phone - Contact*  Phone - Contact*  Product-Env-Stewards  Product-Env-Stewards  Title - Representative*  Title - Representative*  Title - Representative  Product-Env-Stewards  Product-Env-Steward	752-21.1											als and Mfg	g Informat	ion	
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Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Product Enviro Compliance NA Product Enviro Site Weight* UOM Und PANJITFG 310.0 mg Ea  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Requester Item Number Number of Reflow Cycles Requester Item Number NA Product-Env-Stewards@onsemi.com NA Product-Env-Stewards@onsemi.com Na Nanufacturing Site Neight* UOM Und Naturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Nature Time (Sn) - annealed Nature Time (Sn) - annealed Nature Time (Sn) - annealed Nature Time Number Nature Time Numb	ontact Name			Title - Contact			F	Phone - Contact*				Email - Contact*			
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Requester Item Number	Authorized Representative*			Title - Representative			F	Phone - Representative*				Email - Representative*			
DF06S1   BR SDIP PN 1A 600V   2023-06-08   PANJITFG   310.0   mg   Ea	Product-Env-Stewar	rds		Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles  Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	r Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Anufacturing Site	W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  260  Comments			DF06S1		BR SDIP PN 1A 60	)0V		2023-06-08		P	ANJITFG	31	0.0	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				erminal Rose	Alloy	STD-020 MSI	Rating	Peak Proc	ess Rody Te	emperatur	a May Time at Deal-	Temperatu	re Numb	per of Reflow Cya	les
omments					Alloy J-S	31D-020 MSL	Kating		ess Body 16					bei of Kellow Cyc	ies
	•	i (Sii) - aimeaieu	C	O Alloy	1			1200		<u> </u> C	30	second	5   3		
ver 1 - maximum unne at peak temperature uuring soluering is 10-30 seconus		me at neak temperature	during sol	doring is 10-2	10 seconds										
or more information regarding material composition please refer to page 3															

<b>RoHS Material Composition Declaration</b>			Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).							
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the vertification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of hat agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides i									
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).  Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required in Requester) and click on Submit Form to ha		"Accepted" on the Supplier Acceptance drop-do	wn. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature R		,							

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.6	mg	Supplier	Silicon (Si)	7440-21-3		3.3768	mg
			В	Nickel (Ni)	7440-02-0		0.0324	mg
			Supplier	Gold (Au)	7440-57-5		0.018	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.1728	mg
Die Attach Solder	2.595	mg	Supplier	Silver (Ag)	7440-22-4		0.0649	mg
			A	Lead (Pb)	7439-92-1	7a	2.4004	mg
			Supplier	Tin (Sn)	7440-31-5		0.1297	mg
Lead Frame	63.63	mg	Supplier	Iron (Fe)	7439-89-6		0.0764	mg
			Supplier	Copper (Cu)	7440-50-8		63.5346	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0191	mg
Mold Compound-Black	233.175	mg		Metal Hydroxide	proprietary data		8.1611	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		18.654	mg
			Supplier	Carbon Black (C)	1333-86-4		1.1659	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		186.54	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		18.654	mg
Plating	7.0	mg	Supplier	Tin (Sn)	7440-31-5		7	mg